

## PRODUCT CHANGE NOTICE

Dear Lantronix Customer,

The purpose of this communication is to inform you of an upcoming change to the following products. This change is part of our effort and commitment to continuous improvement of our products and processes.

### **Change Type**

Hardware

### **Products Affected**

Part Number	Description	Old Revision	New Revision
QC-SIP-8155-8G	Qualcomm® Snapdragon™ Auto SA8155P SIP 8G LPDDR4X AIT	A	B

### **Description and Extent of Change**

SA8155P SoC has changed to high modulus lid adhesive material and changed to lid foot height from 1.25mm to 1.19mm.

New part will be identified by an updated version:

- QAM-8155P-0-BGM970-MT-01-0-AC

### **Reason for Change**

Decrease thermal performance variation for SA8155P

### **Effect of Change on Fit, Form, Function**

No change in functionality.

SA8155P SoC lid foot height changed from 1.25mm to 1.19mm

### **Effective Date of Change**

This change will go into effect for the listed products built from **May 30, 2023** onwards.

If you have any questions, please contact your sales representative or contact Lantronix Technical Support by submitting a ticket to: <https://ltrxdev.atlassian.net/wiki/spaces/LTRXTS/overview>